

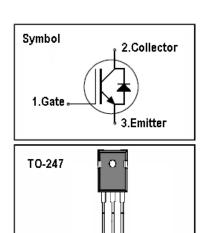
IGBT

Features

- 1200V,25A,V_{CE(sat)(typ.)}=2.5V@V_{GE}=15V
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms



KEDA IGBTs offer lower losses and higher energy efficiency for application such as IH (induction heating), UPS, General inverter and other soft switching applications.



GCE

Absolute Maximum Ratings

| Symbol | Parameter | Value | Units |
|------------------|---|---------------|------------|
| V _{CES} | Collector-Emitter Voltage | 1200 V | |
| V _{GES} | Gate-Emitter Voltage | <u>+</u> 30 V | |
| 1 | Continuous Collector Current (T _C =25 °C) | | А |
| IC | Continuous Collector Current (T _C =100℃) | | А |
| I _{CM} | Pulsed Collector Current (Note 1) | 80 | Α |
| I _F | Diode Continuous Forward Current (T _C =100 ℃) | 15 | Α |
| I _{FM} | Diode Maximum Forward Current (Note 1) | 80 | Α |
| В | Maximum Power Dissipation ($T_C=25 ^{\circ}\mathrm{C}$) | 180 | W |
| P_D | Maximum Power Dissipation (T _C =100 ℃) | 72 | W |
| TJ | Operating Junction Temperature Range | -55 to +150 | $^{\circ}$ |
| T _{STG} | Storage Temperature Range | -55 to +150 | $^{\circ}$ |

Thermal Characteristics

| Symbol | Parameter | Max. | Units |
|---|---|------|--------|
| R _{th j-c} | R _{th j-c} Thermal Resistance, Junction to case for IGBT | | °C / W |
| R _{th j-c} Thermal Resistance, Junction to case for DIODE 0.85 | | °C/W | |
| R _{th j-a} Thermal Resistance, Junction to Ambient 40 | | 40 | °C / W |



$\underline{\textbf{Electrical Characteristics}} \; (\textbf{T}_{\texttt{C}} = \textbf{25} \; \texttt{\^{C}} \; \; \textbf{unless otherwise noted} \;)$

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Units |
|----------------------|--------------------------------------|---|------|------|------|-------|
| BV _{CES} | Collector-Emitter Breakdown Voltage | V _{GE} = 0V, I _C = 250uA | 1200 | - | - | V |
| I _{CES} | Collector-Emitter Leakage Current | V _{CE} = 1200V, V _{GE} = 0V | - | - | 250 | uA |
| | Gate Leakage Current, Forward | V_{GE} =30V, V_{CE} = 0V | - | - | 100 | nA |
| GES | Gate Leakage Current, Reverse | V_{GE} = -30V, V_{CE} = 0V | - | - | -100 | nA |
| V _{GE(th)} | Gate Threshold Voltage | $V_{GE} = V_{CE}$, $I_{C} = 250uA$ | 4.0 | - | 6.0 | V |
| V _{CE(sat)} | Collector-Emitter Saturation Voltage | V_{GE} =15V, I_{C} = 20A | - | 2.4 | 3.0 | V |
| Qg | Total Gate Charge | V _{cc} =960V | - | 150 | 170 | nC |
| Qge | Gate-Emitter Charge | V _{GE} =15V I _C =25A | - | 20 | 30 | nC |
| Qgc | Gate-Collector Charge | | - | 90 | 100 | nC |
| t _{d(on)} | Turn-on Delay Time | V _{cc} =600V | - | 45 | - | ns |
| t r | Turn-on Rise Time | | - | 59 | - | ns |
| t _{d(off)} | Turn-off Delay Time | V _{GE} =15V | - | 375 | - | ns |
| t f | Turn-off Fall Time | I _C =20A R _G =28Ω | - | 210 | - | ns |
| Eon | Turn-on Switching Loss | Inductive Load | - | 2.7 | - | mJ |
| Eoff | Turn-off Switching Loss | T _C =25 ℃ | - | 1.8 | - | mJ |
| Ets | Total Switching Loss | | - | 4.5 | - | mJ |
| C _{ies} | Input Capacitance | V _{CE} =25V V _{GE} =0V | - | 620 | - | pF |
| C _{oes} | Output Capacitance | | - | 109 | - | pF |
| C _{res} | Reverse Transfer Capacitance | f = 1kHz | - | 46 | - | pF |
| R _{Gint} | Integrated gate resistor | | 1.85 | 1.9 | 1.95 | Ω |

Electrical Characteristics of Diode (T_C=25 ℃ unless otherwise noted)

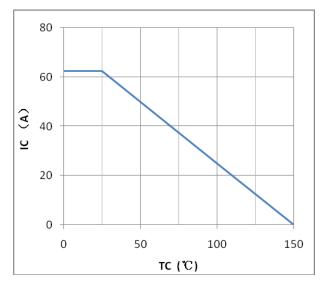
| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Units |
|------------------|-------------------------------------|------------------------|------|------|------|-------|
| V _F | Diode Forward Voltage | I _F =15A | - | 1.4 | 2.0 | V |
| trr | Diode Reverse Recovery Time | V _{CE} = 600V | - | 209 | | ns |
| Irr | Diode peak Reverse Recovery Current | I _F =15A | - | 26 | | Α |
| Q _{r r} | Diode Reverse Recovery Charge | $dI_F/dt = 500A/us$ | - | 3300 | | nC |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



Typical Performance Characteristics



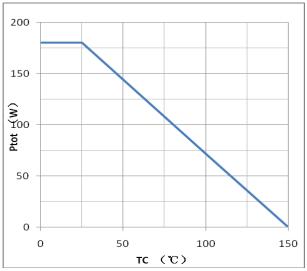
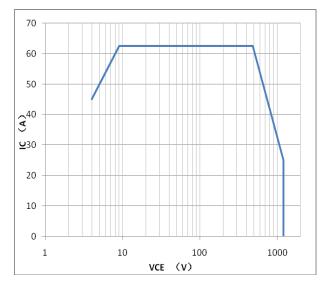


Figure1:maximum DC collector current VS. case temprature

Figure2:power dissipation VS. case temprature



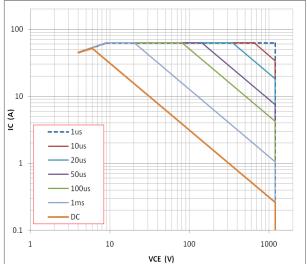
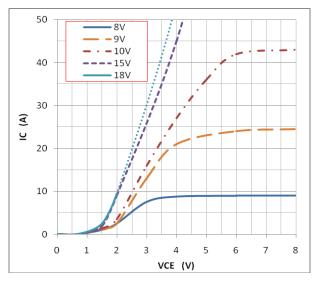


Figure3:reverse bias SOA,TJ=150 $^{\circ}$ C,VGE=15V

Figure4:forward SOA,TC=25 $^{\circ}$ C,TJ \leqslant 150 $^{\circ}$ C



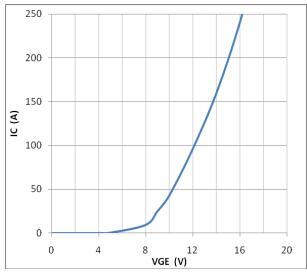
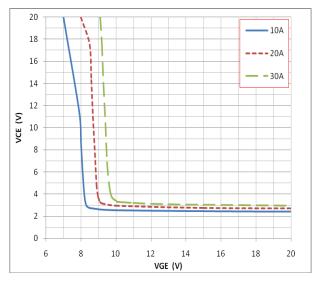


Figure5:typical IGBT output characteristics, $\label{eq:TJ=25\,C;tp=300us} TJ=25\,^{\circ}C;tp=300us$

Figure6:typical trans characteristics, VCE=20V,tp=20us



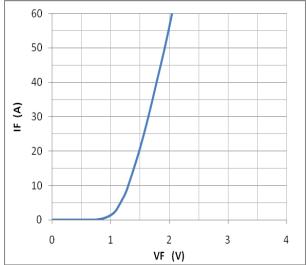
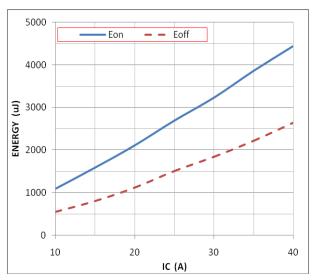


Figure7: typical VCE VS. VGE,TJ=25°C

Figure8:typical diode forward characteristic,tp=300us



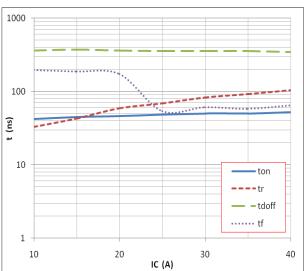
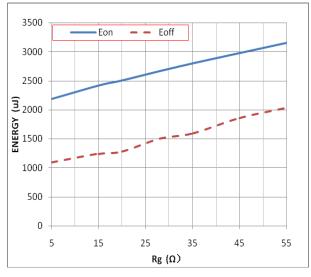


Figure9: typical energy loss VS. IC, TC=25°C,

L=500uH, VCE=600V,VGE=15V,Rg= 28Ω

Figure 10: typical switching time VS. IC, TC=25°C,

L=500uH, VCE=600V,VGE=15V,Rg=28 Ω



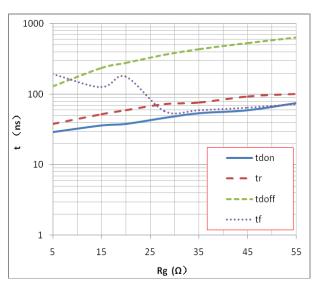
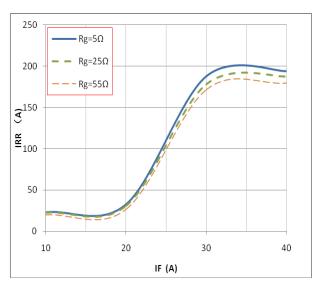


Figure11: typical energy loss VS. Rg,TC=25°C,

L=500uH, VCE=600V, VGE=15V,IC=25A

Figure 12: typical switching time VS. Rg,TC=25°C,

L=500uH,VCE=600V,VGE=15V,IC=25A



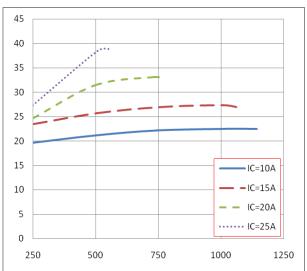
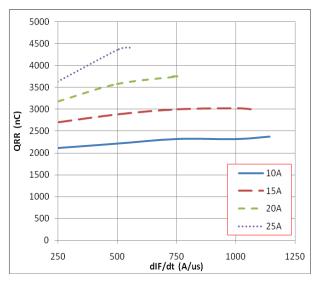


Figure 13: typical diode IRR VS. IF, TC=25°C

VCC=600V, VGE=15V

Figure14:typical diode IRR VS. dIF/dt

VCC=600V,VGE=15V



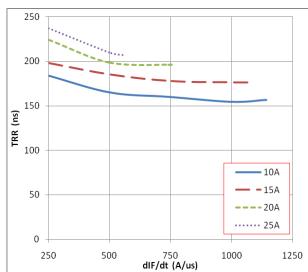
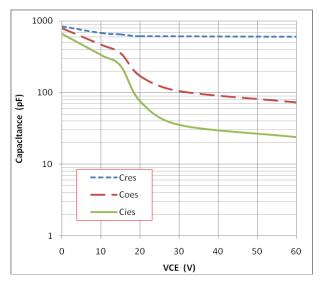


Figure15:typical diode QRR VS. dIF/dt

VCC=600V,VGE=15V

Figure16:typical diode TRR VS. dIF/dt,

VCC=600V,VGE=15V



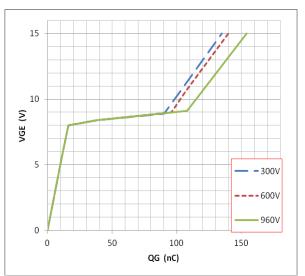


Figure17:typical capacitance VS. VCE,VGE=0V,f=100kHz

Figure 18: typical gate charge VS. VGE, IC=25A

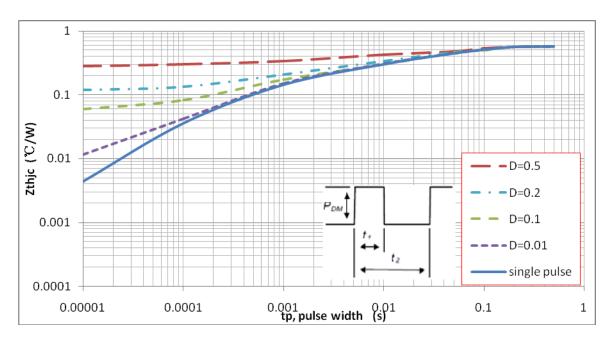
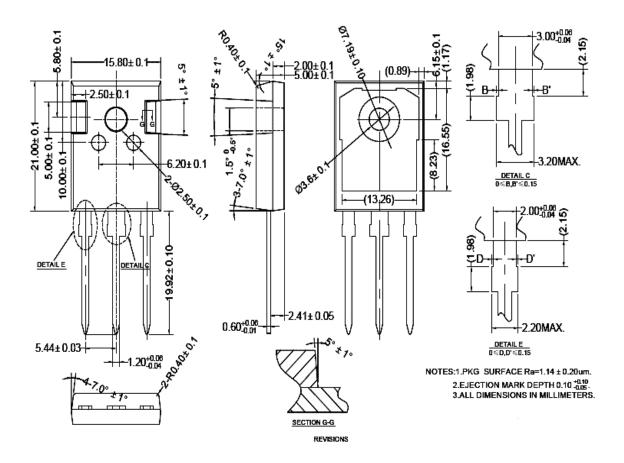


Figure 19: normalized transient thermal impedance, junction-to-case

Note1.Duty factor D=t1/t2; Note2:peak TJ=PDM×Zthjc+TC



TO247 PACKAGE OUTLINE



| 公差标注 | 公差值 | 表面粗糙度 |
|--------|--------|-----------|
| 0 | ±0.2 | Ra3.2~6.3 |
| 0.0 | ±0.1 | Ra1.6~3.2 |
| 0.00 | ±0.01 | Ra0.8~1.6 |
| 0.000 | ±0.005 | Ra0.4~0.8 |
| 0.0000 | ±0.002 | Ra0.2~0.4 |

0≤D,D'≤0.15

NOTES:1.PKG SURFACE Ra=1.14 ± 0.20um. 2.EJECTION MARK DEPTH 0.10 +0.10 3.ALL DIMENSIONS IN MILLIMETERS.





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